## Development of a Package for a Triaxial High-G Accelerometer Optimized for High Signal Fidelity

#### **Ralph Langkemper**

Robert Külls, Jürgen Wilde, Siegfried Nau, Sebastian Schopferer

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#### AGENDA

- What is "high-g"
- Goal and Requirements
- Numeric Simulation
  - Package Design
  - Simulation Methods
  - Results
- Experimental Tests
  - Realised Prototype
  - Eigenfrequency
  - Triaxial Measurement
- Summary





## What is "high-g"

- Examples for acceleration:
  - Gravity 9,81m/s<sup>2</sup> ≙ 1 g
  - Limit for roller coaster 6 g
  - Breaking point of humans 10 g
  - Crashtests 50-100 g
  - Testing sensors and electronics 1.000 g

- Special application "high-g":
  - Material characterization 100.000 g
  - Ballistic experiments 100.000 g





#### **Goal and Requirements**

- Starting point of this work:
  - Piezoresistive sensor chip
  - 3D-setup on Al<sub>2</sub>O<sub>3</sub>-ceramic plate
    - $\rightarrow$  Sensor element
  - Uniqueness:
    - standing sensor chip for Z-axis
    - 90° contacting via Aerosol-print-jet







#### **Goal and Requirements**

Development of a Package for a Triaxial High-G Accelerometer

Wired

- Shock-proof (up to 100.000 g)
- Electromagnetic shielding
- Functional for -40 80° C
- High bandwidth (aim: 100 kHz)
  - Max. 5%-deviation
- Characterization of first prototype
  - $\rightarrow$  Functional, robust and feasible sensor





#### Numeric Simulation Package Design





#### Numeric Simulation Simulation Methods

- Modal analysis:
  - Shape and frequency of the Eigen modes of the sensor
- Frequency spectrum analysis:
  - Excitation frequency varied
  - Computing of the electrical output signal of the sensor at
    - 100.000 g
    - 1 V supply voltage
- Use of COMSOL Multiphysics
  - Structural Mechanics
  - LiveLink for Inventor





- Used package parameters:
  - Material: Titanium (E/p = 26,4)
  - Wall thickness: 1 mm
  - Cap thickness: 0,2 mm

- Adhesive: epoxy (Young's modulus: 2,5 GPa)
- Adhesive layer sensor element:
  50 µm
- Adhesive layer sensor: 20 µm





- First mode: 39 kHz
  - Oscillation of the cap
  - Only little influence on the sensor signal





- Package mode: 128 kHz
  - First mode with noticable movement within the package
  - Quite high influence on the sensor element





- Sensor element mode: 287 kHz
  - Mode with main displacement within the sensor element
  - Expected to be main influence on the sensor signal
  - Frequency was not simulated







#### **Experimental Tests Realised Prototype**

- Prototype parameters:
  - Wall thickness: 1,5 mm
  - Cap thickness: 0,2 mm
  - Material: Titanium
  - Adhesive layers
    - Thickness: 20-70 µm
    - Young's modulus: 0,56 GPa

#### Adapted simulation:



Layer thickness	5%-limit	Package mode	Sensor element mode
20 µm	30 kHz	98 kHz	200 kHz
70 µm	16 kHz	67 kHz	129 kHz



## Experimental Tests Eigenfrequency

- Excitation of sensor via a transient impulse
  - FFT of the signal

→ Frequency spectrum of the signal

Relevant Eigen frequencies

→ Peak within the spectrum





## Experimental Tests Eigenfrequency

- Eigen frequency of the sensor chip:
  - Expected: 1 MHz
  - Measurement: 930 kHz
- Influence of the package:
  - Expected among 129-200kHz
  - Measurement: 153 kHz

→ Measured values coincide with the results of the numeric simulation





## Experimental Tests Eigenfrequency

- Eigen frequency of the sensor chip:
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#### **Experimental Tests Triaxial Measurement**

- Acceleration on all three axes
  - Uniaxial Shock divided to all axes equally due to attachment angle
  - Impulse: 8600 g each axis
  - Expected sensitivity:
    - 1,30 µV/V/g (± 30%)
- Measured sensitivity
  - X-axis: 1,00 µV/V/g
  - Y-axis: 1,33 µV/V/g
  - Z-axis: 1,30 µV/V/g
  - → Corresponds with the expected values of simulation and previous work





#### Summary

- A package was designed and modelled
- Its behaviour was examined via simulation
- A prototype was built and characterized
- The simulation could be verified with the experimental results





# Thank you for your attention!

Contact:

Ralph Langkemper Fraunhofer Ernst-Mach-Institut Ralph.Langkemper@emi.fhg.de Tel: 07628/90 50 637





